

DESCRIPTION

The SPN1012 is the N-Channel enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance and provide superior switching performance. These devices are particularly suited for low voltage applications such as notebook computer power management and other battery powered circuits where high-side switching, low in-line power loss, and resistance to transients are needed.

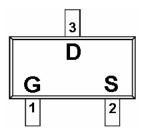
APPLICATIONS

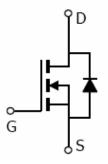
- Drivers : Relays/Solenoids/Lamps/Hammers
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

FEATURES

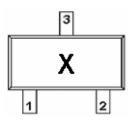
- N-Channel 20V/0.65A,RDS(ON)=380mΩ@VGS=4.5V 20V/0.55A,RDS(ON)=450mΩ@VGS=2.5V 20V/0.45A,RDS(ON)=800mΩ@VGS=1.8V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOT-523 (SC-89) package design

PIN CONFIGURATION(SOT-523/SC-89)





PART MARKING



PIN DESCRIPTION					
Pin	Symbol	Description			
1	G	Gate			
2	S	Source			
3	D	Drain			

ORDERING INFORMATION

Part Number	Package Part Marking	
SPN1012S52RG	SOT-523	X

※ SPN1012S52RG : Tape Reel ; Pb − Free

ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

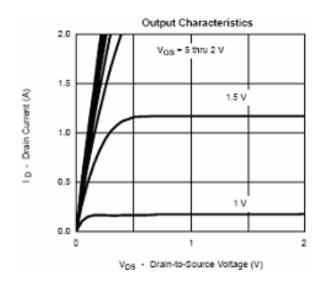
Parameter		Symbol	Typical	Unit	
Drain-Source Voltage		Vdss	20	V	
Gate –Source Voltage		Vgss	±12	V	
C (D C (T- 150°C)	TA=25°C	ID	0.65	Α	
Continuous Drain Current(T₁=150°C)	Ta=80°C	ID	0.45		
Pulsed Drain Current		IDM	1.0	Α	
Continuous Source Current(Diode Conduction)		Is	0.3	Α	
Power Dissipation	TA=25°C	PD	0.27	W	
	Ta=70°C	PD	0.16		
Operating Junction Temperature		Тл	-55/150	$^{\circ}\!\mathbb{C}$	
Storage Temperature Range		Tstg	-55/150	$^{\circ}\!\mathbb{C}$	

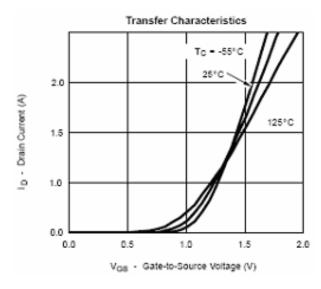
ELECTRICAL CHARACTERISTICS

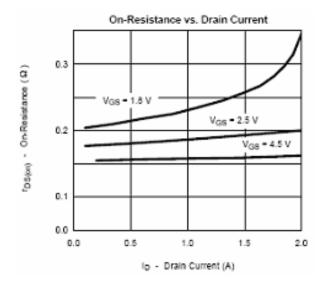
(Ta=25°C Unless otherwise noted)

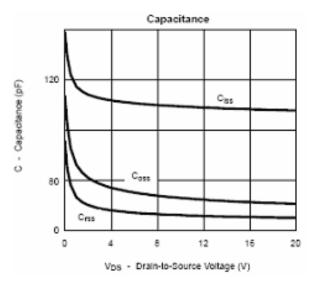
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V(BR)DSS	V _G S=0V,I _D = 250uA	20			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	0.35		1.0]	
Gate Leakage Current	Igss	V _{DS} =0V,V _{GS} =±12V			100	nA	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 20V,V _{GS} =0V V _{DS} = 20V,V _{GS} =0V T _J =55°C			5	uA	
On-State Drain Current	ID(on)	$V_{DS} \ge 4.5 \text{V}, V_{GS} = 5 \text{V}$	0.7			Α	
Drain-Source On-Resistance	RDS(on)	V _{GS} =4.5V,I _D =0.65A V _{GS} =2.5V,I _D =0.55A V _{GS} =1.8V,I _D =0.45A		0.26 0.32 0.42	0.38 0.45 0.80	Ω	
Forward Transconductance	gfs	V _{DS} =10V,I _D =0.4A		1.0		S	
Diode Forward Voltage	Vsd	Is=0.15A,VGS=0V		0.8	1.2	V	
Dynamic							
Total Gate Charge	Qg	V _{DS} =10V,V _{GS} =4.5V,		1.2	1.5	nC	
Gate-Source Charge	Qgs	ID≡0.6A		0.2			
Gate-Drain Charge	Qgd	1		0.3			
Turn-On Time	td(on)	$V_{DD}=10V_{,RL}=10\Omega$,		5	10	ns	
	tr	ID=0.5A		8	15		
T. OMT.	td(off)	$V_{GEN}=4.5V$, $R_{G}=6\Omega$		10	18		
Turn-Off Time	tf			1.2	2.8		

TYPICAL CHARACTERISTICS

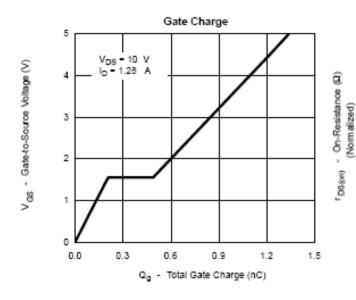


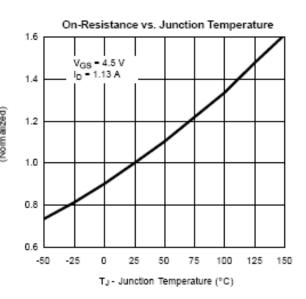


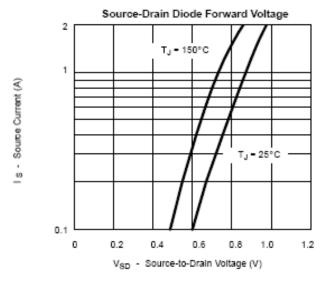


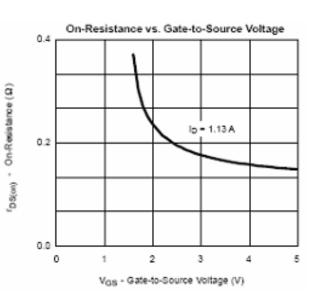


TYPICAL CHARACTERISTICS



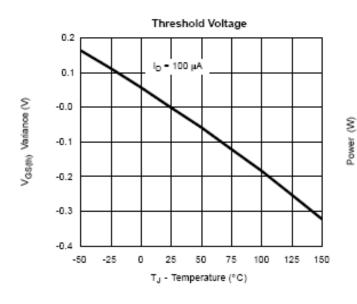


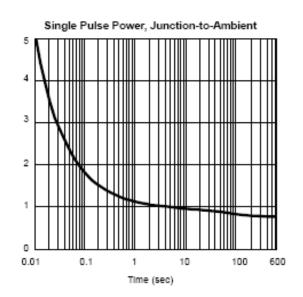




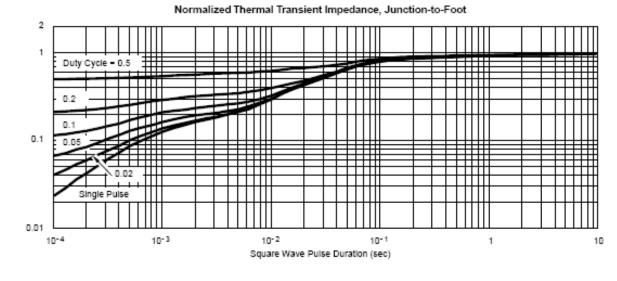
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TYPICAL CHARACTERISTICS



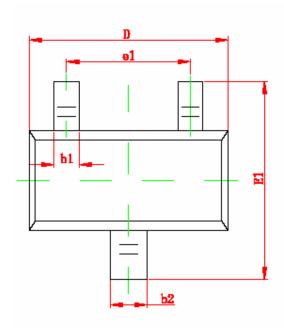


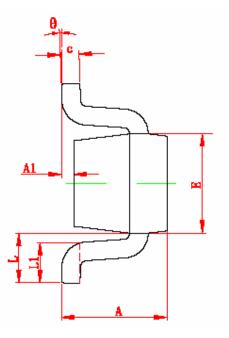


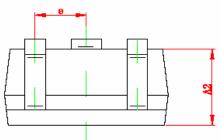




SOT-523 PACKAGE OUTLINE







Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.150	0.250	0.006	0.010	
b2	0.250	0.325	0.010	0.013	
С	0.100	0.200	0.004	0.008	
D	1.500	1.700	0.059	0.067	
E	0.750	0.850	0.030	0.033	
E1	1.450	1.750	0.057	0.069	
е	0.500 TYP		0.020) TYP	
e1	0.900	1.100	0.035	0.043	
L	0.550 REF		0.022 REF		
L1	0.280	0.440	0.011	0.017	
θ	0°	4°	0°	4°	

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